

# **ALIGNMENT MARK AND EXPOSURE ALIGNMENT SYSTEM AND METHOD USING THE SAME**

## **ABSTRACT**

An alignment mark and an exposure alignment system and method using the alignment mark for aligning wafers are described. The alignment mark is formed of a plurality of mesa or trench type unit marks that are aligned in an inline pattern within an underlying layer under a layer to which a chemical mechanical polishing process is applied to form an alignment signal during an alignment process, thereby preventing a dishing phenomenon caused by the chemical mechanical process.

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